



7106DG

Surface Mount



Surface mount heat sink for D2 Pak (TO-263) power SO-10 (MO-184) package semiconductors

This non-electronic component is functionally unaffected by the normal soldering or reflow processes used for semiconductor circuits. The heat resistance time or heat resistance temperature is not applicable for the component.

Height:

9.65

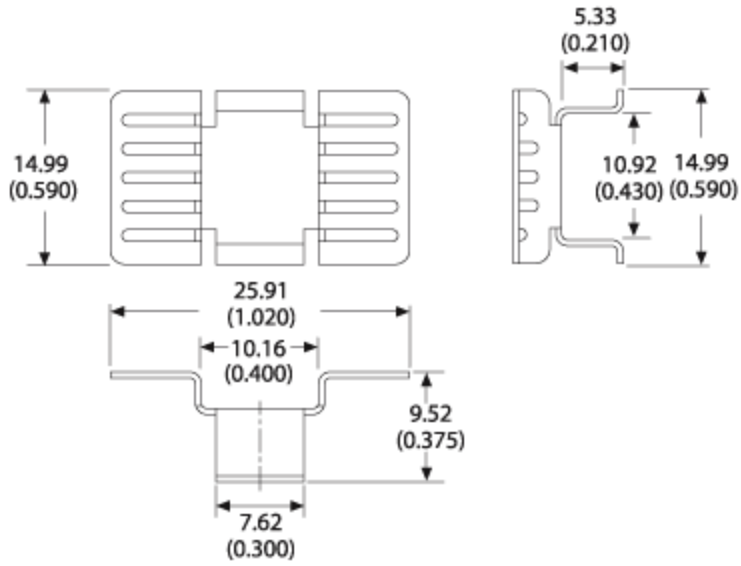
Mount Orientation:

Horizontal

Finish: Tin Plated

Thermal Resistance:

15.0



Recommended copper pad size for heat sink and device mounting footprint

